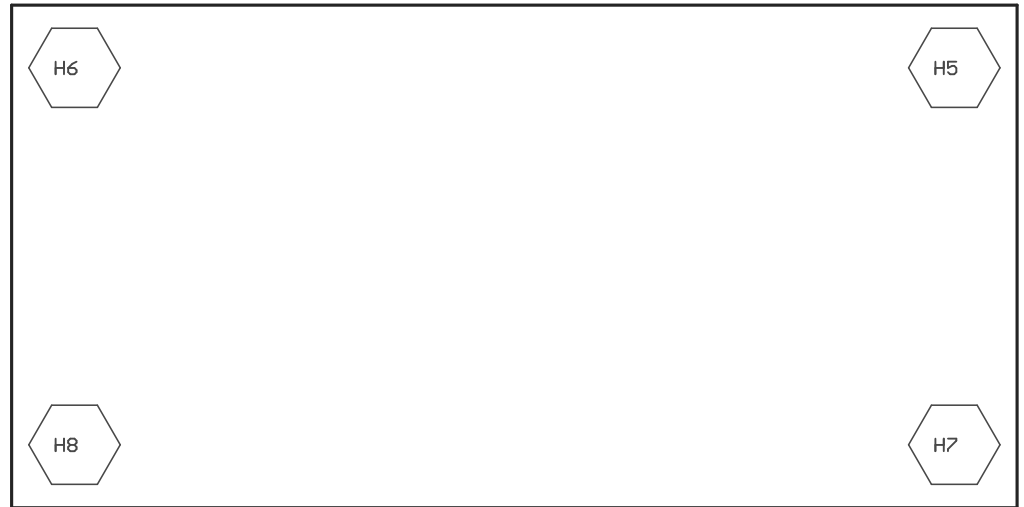


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 11/30/2017 5:42:58 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED	: 11/30/2017 5:42:59 PM	TEXAS INSTRUMENTS

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